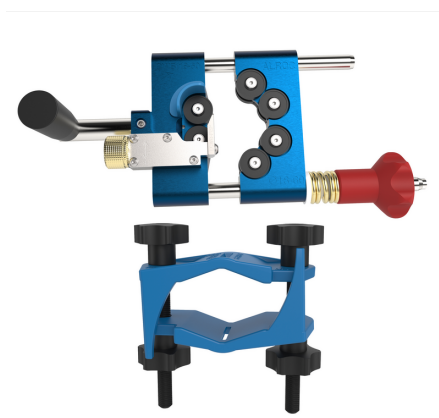




See online
technical sheet

/ CWB/18-60-MVS-8

Tool to remove bonded semiconductor with chamfer on the semiconductor cutback and stop for MV cable



/ Use

The CWB/18-60-MVS-8 enables the user to easily remove the bonded semi-conductor without silicon and with a chamfer on the semicon cutback. The MVS sits on the cable to stop the CWB/18-60-MVS-8 with a large contact surface.

/ Advantages

- No silicon needed
- Cutting depth with 1/10 mm increments
- Smooth finish
- Robust design
- Easy to get to grips with

/ Areas of activity

-  Cable & Connections
-  Substation
-  Electrical distribution
-  Industry

/ Technical specifications

- **Specific tools :** Cable tools
- **Cable tools :** Cable tools
- **Areas of activity :** Cable & Connections, Electrical distribution, Industry, Substation
- **For network cables :** medium voltage
- **Packaging :** Carton box
- **Weight (g) :** 900
- **Lenght (mm) :** 235
- **Width (mm) :** 125
- **Height (mm) :** 90
- **Max diameter (mm) :** 60
- **Mini diameter (mm) :** 18
- **Cut deepness (mm) :** 1,8
- **Chamfer angle (°) :** 8
- **Tools king :** Specific tools

/ Spare parts

	Reference	Designation
	LCWB-SP2	Blade for bonded semi-conductor 8°